# SN65C1154, SN75C1154 QUADRUPLE LOW-POWER DRIVERS/RECEIVERS

SLLS151D - DECEMBER 1988 - REVISED APRIL 2003

 Meet or Exceed the Requirements of TIA/EIA-232-F and ITU Recommendation V 28

- Very Low Power Consumption . . .5 mW Typ
- Wide Driver Supply Voltage . . . ±4.5 V to ±15 V
- Driver Output Slew Rate Limited to 30 V/μs Max
- Receiver Input Hysteresis . . . 1000 mV Typ
- Push-Pull Receiver Outputs
- On-Chip Receiver 1-μs Noise Filter

#### SN65C1154...N PACKAGE SN75C1154 . . . DW. N. OR NS PACKAGE (TOP VIEW) 20 🛮 V<sub>CC</sub> $V_{DD}$ 1RA 🛮 2 19 1 1RY 18 🛮 1DA 1DY [] 3 2RA **∏** 4 17 **∏** 2RY 2DY **∏** 5 16 2DA 15 3RY 3RA 🛮 6 3DY 🛮 7 14 ¶ 3DA 4RA **∏** 8 13 **∏** 4RY 12 **]** 4DA 4DY 🛮 9 11 GND

#### description/ordering information

The SN65C1164 and SN75C1154 are low-power BiMOS devices containing four independent drivers and receivers that are used to interface data terminal equipment (DTE) with data circuit-terminating equipment (DCE). These devices are designed to conform to TIA/EIA-232-F. The drivers and receivers of the SN65C1154 and SN75C1154 are similar to those of the SN75C188 quadruple driver and SN75C189A quadruple receiver, respectively. The drivers have a controlled output slew rate that is limited to a maximum of 30 V/ $\mu$ s and the receivers have filters that reject input noise pulses of shorter than 1  $\mu$ s. Both these features eliminate the need for external components.

The SN65C1154 and SN75C1154 have been designed using low-power techniques in a BiMOS technology. In most applications, the receivers contained in these devices interface to single inputs of peripheral devices such as ACEs, UARTs, or microprocessors. By using sampling, such peripheral devices usually are insensitive to the transition times of the input signals. If this is not the case, or for other uses, it is recommended that the SN65C1154 and SN75C1154 receiver outputs be buffered by single Schmitt input gates or single gates of the HCMOS, ALS, or 74F logic families.

#### ORDERING INFORMATION

TA	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP (N)	Tube of 20	SN65C1154N	SN65C1154N
	PDIP (N)	Tube of 20	SN75C1154N	SN75C1154N
0°C to 70°C	SOIC (DW)	Tube of 25	SN75C1154DW	SN75C1154
0.0 10 70.0	SOIC (DVV)	Reel of 2500	SN75C1154DWR	3117301134
	SOP (NS)	Reel of 2000	SN75C1154NSR	SN75C1154

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



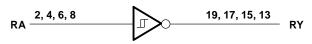
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## logic diagram (positive logic)

Typical of Each Receiver

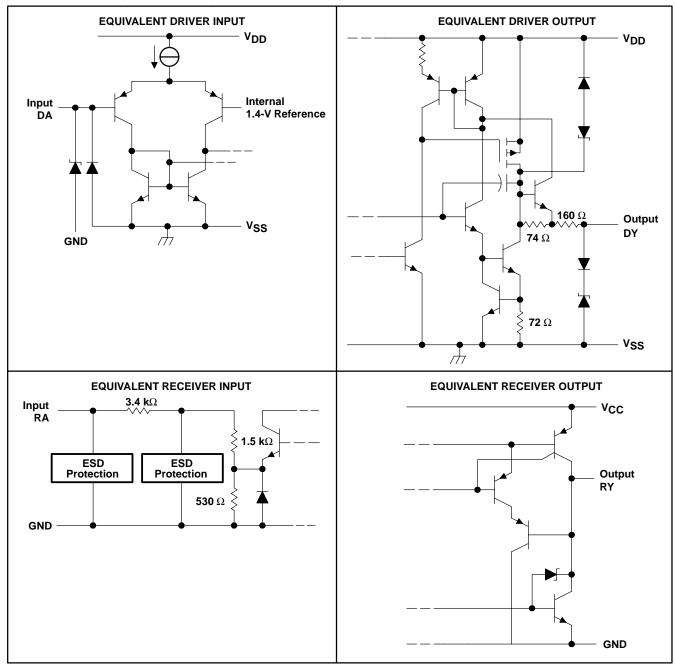


**Typical of Each Driver** 





# schematics of inputs and outputs



Resistor values shown are nominal.

# SN65C1154, SN75C1154 QUADRUPLE LOW-POWER DRIVERS/RECEIVERS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage: V <sub>DD</sub> (see Note 1)	15 V
V <sub>SS</sub>	
V <sub>CC</sub>	7 V
Input voltage range, V <sub>I</sub> : Driver	$V_{SS}$ to $V_{DD}$
Receiver	
Output voltage range, V <sub>O</sub> :Driver	
Receiver	0.3 V to (V <sub>CC</sub> + 0.3 V)
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3):	DW package 58°C/W
	N package 69°C/W
	NS package 60°C/W
Operating virtual junction temperature, T <sub>J</sub>	
Storage temperature range, T <sub>stq</sub>	
Lead temperature 1,6 mm (1/16 inch) from case for 10 s	seconds

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage s are with respect to the network GND terminal.
  - 2. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions

			MIN	NOM	MAX	UNIT
$V_{DD}$	V <sub>DD</sub> Supply voltage		4.5	12	15	V
VSS	Supply voltage		-4.5	-12	-15	V
Vcc	Supply voltage		4.5	5	6	V
VI	Input voltage	Driver	V <sub>SS</sub> + 2		$V_{DD}$	V
	Input voltage	Receiver			±25	
VIH	High-level input voltage	Driver	2			V
V <sub>IL</sub>	Low-level input voltage	Driver			0.8	٧
ЮН	High-level output current	Receiver			-1	mA
l <sub>OL</sub>	High-level output current	Receiver			3.2	mA
т.	Operating free-air temperature	SN65C1154	-40		85	°C
TA	SN75C1154		0		70	



#### **DRIVER SECTION**

# electrical characteristics over operating free-air temperature range, $V_{DD}$ = 12 V, $V_{SS}$ = –12 V, $V_{CC}$ = 5 V $\pm 10\%$ (unless otherwise noted)

	PARAMETER	TEST CONDITIONS				MIN	TYP†	MAX	UNIT
Va	High lavel autout valtage	$V_{IL} = 0.8 V$ ,	$R_L = 3 k\Omega$ ,	$V_{DD} = 5 V$ ,	$V_{SS} = -5 V$	4	4.5		V
VOH	High-level output voltage	See Figure 1		$V_{DD} = 12 V$ ,	$V_{SS} = -12 \text{ V}$	10	10.8		
\/o!	Low-level output voltage	V <sub>IH</sub> = 2 V,	$R_L = 3 k\Omega$ ,	$V_{DD} = 5 V$ ,	$V_{SS} = -5 V$		-4.4	-4	V
VOL	(see Note 4)	See Figure 1		$V_{DD} = 12 V$ ,	$V_{SS} = -12 \text{ V}$		-10.7	-10	٧
lн	High-level input current	V <sub>I</sub> = 5 V,	See Figure 2					1	μΑ
Ι <sub>Ι</sub> L	Low-level input current	$V_{I} = 0,$	See Figure 2					-1	μΑ
IOS(H)	High-level short-circuit output current‡	V <sub>I</sub> = 0.8 V,	$V_O = 0$ or $V_{SS}$ ,	See Figure 1		-7.5	-12	-19.5	mA
IOS(L)	Low-level short-circuit output current‡	V <sub>I</sub> = 2 V,	$V_O = 0$ or $V_{DD}$ ,	See Figure 1		7.5	12	19.5	mA
Inn	Supply current from VDD	No load,		$V_{DD} = 5 V$ ,	$V_{SS} = -5 V$		115	250	μΑ
IDD	Supply current from VDD	All inputs at 2 V	/ or 0.8 V	$V_{DD} = 12 V$ ,	$V_{SS} = -12 \text{ V}$		115	250	μΑ
loo	A Complete company for an V		No load,		$V_{SS} = -5 V$		-115	-250	^
Iss	Supply current from VSS	All inputs at 2 V or 0.8 V $V_{DD} = 12$		V <sub>DD</sub> = 12 V,	V <sub>SS</sub> = -12 V		-115	-250	μΑ
ro	Output resistance	$V_{DD} = V_{SS} = V_{DD}$	$V_{CC} = 0$ , $V_{O} = -2$	2 V to 2 V,	See Note 5	300	400	Ö	Ω

<sup>†</sup> All typical values are at  $T_A = 25^{\circ}C$ .

NOTES: 4. The algebraic convention, where the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic levels only.

5. Test conditions are those specified by TIA/EIA-232-F.

## switching characteristics, $V_{DD}$ = 12 V, $V_{SS}$ = –12 V, $V_{CC}$ = 5 V ±10%, $T_A$ = 25°C (see Figure 3)

	PARAMETER		TEST CONDITIONS			MAX	UNIT
tPLH	Propagation delay time, low- to high-level output§	$R_L = 3 \text{ to } 7 \text{ k}\Omega$	CL = 15 pF		1.2	3	μs
tPHL	Propagation delay time, high- to low-level output§	$R_L = 3 \text{ to } 7 \text{ k}\Omega$	CL = 15 pF		2.5	3.5	μs
tTLH	Transition time, low- to high-level output¶	$R_L = 3 \text{ to } 7 \text{ k}\Omega$	CL = 15 pF	0.53	2	3.2	μs
tTHL	Transition time, high- to low-level output¶	$R_L = 3 \text{ to } 7 \text{ k}\Omega$	CL = 15 pF	0.53	2	3.2	μs
tTLH	Transition time, low- to high-level output#	$R_L = 3 \text{ to } 7 \text{ k}\Omega$	C <sub>L</sub> = 2500 pF		1	2	μs
tTHL	Transition time, high- to low-level output#	$R_L = 3 \text{ to } 7 \text{ k}\Omega$	C <sub>L</sub> = 2500 pF		1	2	μs
SR	Output slew rate	$R_L = 3 \text{ to } 7 \text{ k}\Omega$	CL = 15 pF	4	10	30	V/μs

<sup>§</sup> tpHL and tpLH include the additional time due to on-chip slew rate control and are measured at the 50% points.



<sup>‡</sup> Not more than one output should be shorted at one time.

<sup>¶</sup> Measured between 10% and 90% points of output waveform

<sup>#</sup> Measured between 3 V and –3 V points of output waveform (TIA/EIA-232-F conditions) with all unused inputs tied either high or low

#### **RECEIVER SECTION**

### electrical characteristics over operating free-air temperature range, $V_{DD} = 12 \text{ V}$ , $V_{SS} = -12 \text{ V}$ , $V_{CC}$ = 5 V ± 10% (unless otherwise noted)

PARAMETER		TEST CONDITIONS			TYP <sup>†</sup>	MAX	UNIT	
V <sub>IT+</sub>	Positive-going input threshold voltage	See Figure 5			2.1	2.55	٧	
V <sub>IT</sub> –	Negative-going input threshold voltage	See Figure 5		0.65	1	1.25	٧	
V <sub>hys</sub>	Input hysteresis voltage (V <sub>IT+</sub> - V <sub>IT-</sub> )			600	1000		mV	
		$V_I = 0.75 \text{ V}, \qquad I_{OH} = -20 \mu\text{A},$	See Figure 5 and Note 6	3.5				
\/o	High-level output voltage	V 0.75 V 1 4 4	V <sub>CC</sub> = 4.5 V	2.8	4.4		V	
VOH		$V_I = 0.75 \text{ V},  I_{OH} = -1 \text{ mA},$ See Figure 5	V <sub>CC</sub> = 5 V	3.8	4.9		]	
		ess i igais s	V <sub>CC</sub> = 5.5 V	4.3	5.4		]	
VOL	Low-level output voltage	$V_I = 3 V$ , $I_{OL} = 3.2 \text{ mA}$ ,	See Figure 5		0.17	0.4	V	
lu i	High-level input current	V <sub>I</sub> = 25 V		3.6	4.6	8.3	mA	
ΊΗ	nigh-level input current	V <sub>I</sub> = 3 V	0.43	0.55	1	mA		
l	Low-level input current	V <sub>I</sub> = -25 V		-3.6	<b>–</b> 5	-8.3	3 mA	
ΙIL	Low-level input current	V <sub>I</sub> = −3 V			-0.55	-1	ША	
IOS(H)	Short-circuit output at high level	$V_I = 0.75 \text{ V},  V_O = 0,$	See Figure 4		-8	-15	mA	
los(L)	Short-circuit output at low level	$V_I = V_{CC},$ $V_O = V_{CC},$	See Figure 4		13	25	mA	
laa	Supply current from V <sub>CC</sub>	No load,	$V_{DD} = 5 \text{ V},  V_{SS} = -5 \text{ V}$		400	600	۸	
ICC	Subbis carrett trout ACC	All inputs at 0 or 5 V $V_{DD} = 12 \text{ V}$ , $V_{SS} = -12 \text{ V}$			400	600	μΑ	

 $^{\dagger}$  All typical values are at  $T_A = 25^{\circ}$ C. NOTE 6: If the inputs are left unconnected, the receiver interprets this as an input low and the receiver outputs will remain in the high state.

## switching characteristics, $V_{DD}$ = 12 V, $V_{SS}$ = -12 V, $V_{CC}$ = 5 V $\pm$ 10%, $T_A$ = 25°C

	PARAMETER		TEST CONDITIONS			TYP	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low- to high-level output	C <sub>L</sub> = 50 pF,	$R_L = 5 k\Omega$ ,	See Figure 6		3	4	μs
<sup>t</sup> PHL	Propagation delay time, high- to low-level output	C <sub>L</sub> = 50 pF,	$R_L = 5 \text{ k}\Omega$ ,	See Figure 6		3	4	μs
<sup>t</sup> TLH	Transition time, low- to high-level output	$C_L = 50 \text{ pF},$	$R_L = 5 k\Omega$ ,	See Figure 6		300	450	ns
tTHL	Transition time, high- to low-level output	C <sub>L</sub> = 50 pF,	$R_L = 5 k\Omega$ ,	See Figure 6		100	300	ns
tw(N)	Duration of longest pulse rejected as noise‡	C <sub>L</sub> = 50 pF,	$R_L = 5 \text{ k}\Omega$		1		4	μs

 $<sup>^{\</sup>ddagger}$  The receiver ignores any positive- or negative-going pulse that is less than the minimum value of  $t_{W(N)}$  and accepts any positive- or negative-going pulse greater than the maximum of  $t_{W(N)}$ .



#### PARAMETER MEASUREMENT INFORMATION

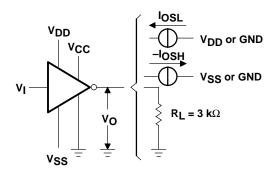


Figure 1. Driver Test Circuit  $(V_{OH}, V_{OL}, I_{OSL}, I_{OSH})$ 

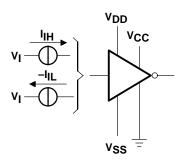
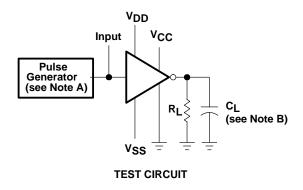
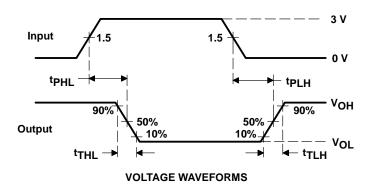


Figure 2. Driver Test Circuit (I<sub>IL</sub>, I<sub>IH</sub>)





NOTES: A. The pulse generator has the following characteristics:  $t_W$  = 25  $\mu$ s, PRR = 20 kHz,  $Z_O$  = 50  $\Omega$ ,  $t_f$  =  $t_f$  < 50 ns.

B. C<sub>L</sub> includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms

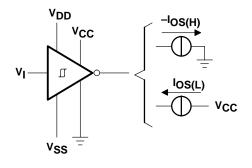


Figure 4. Receiver Test Circuit (I<sub>OSH</sub>, I<sub>OSL</sub>)

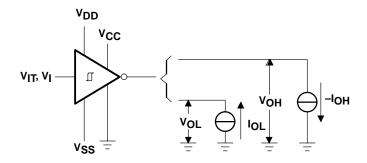
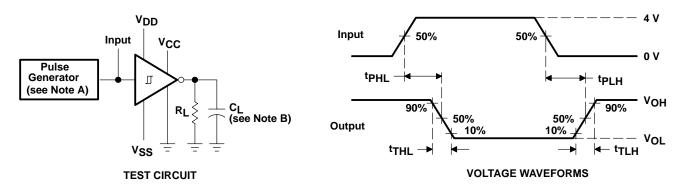


Figure 5. Receiver Test Circuit (V<sub>IT</sub>, V<sub>OL</sub>, V<sub>OH</sub>)

#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The pulse generator has the following characteristics:  $t_W$  = 25  $\mu$ s, PRR = 20 kHz,  $Z_O$  = 50  $\Omega$ ,  $t_\Gamma$  =  $t_f$  < 50 ns.
  - B. C<sub>L</sub> includes probe and jig capacitance.

Figure 6. Receiver Test Circuit and Voltage Waveforms



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# DW (R-PDSO-G20)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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